DON N		20221005	000 14		DC	N. D. L.	December 14,
PCN Number: 202		20231005	0231005000.1A		PC	N Date:	2023
Title: Qualify additional Assembly site for select SOT-5X3 Package devices							
Custom	er Contact:		nagement team			Quality Services	
Proposed 1 st Ship Date:			Jan 13, 2024 Mar 14, 2024 (rev A)		•		
*Sample	requests receiv	ved after J	an 14, 2024 will	not be supp	orted.		
Change	Type:						
	Assembly Site		Design			Wafer Bump Material	
	Assembly Process		☐ Data Sheet			Wafer Bump Process	
	embly Materials		Part number	r change		Wafer Fab Site	
	hanical Specific		☐ Test Site			Wafer Fab Materials	
	king/Shipping/L	abeling	☐ Test Proces			Wafer F	ab Process
			PCN De	etails			
	tion of Change						
<mark>notificati</mark>	<mark>ion. The new d</mark>	<mark>evice is hig</mark>		<mark>lded</mark> in the	device		on the original PCN u. The proposed 1 st
devices listed below in the product affected section. Construction differences and current assembly sites are as follows:							
Λ.	Accombly Sites HNA DHI CDAT ICETCS						
	ssembly Sites						
	ssembly Sites		HNA, PHI, CDA	T, JCETC8			
	ssembly Sites ead Finish		HNA, PHI, CDA NiPdAu, Matte	T, JCETC8			
Le	ead Finish		HNA, PHI, CDA NiPdAu, Matte 400194	T, JCETC8			
Le	•	d	HNA, PHI, CDA NiPdAu, Matte 400194 4226215	T, JCETC8 Sn			
Le	ead Finish	i	HNA, PHI, CDA NiPdAu, Matte 400194 4226215 4226215 + 42	T, JCETC8 Sn			
M	ead Finish Iount Compound	i	HNA, PHI, CDA NiPdAu, Matte 400194 4226215 4226215 + 42 450214	T, JCETC8 Sn 21460			
M	ead Finish	i	HNA, PHI, CDA NiPdAu, Matte 400194 4226215 4226215 + 42 450214 131010100455	T, JCETC8 Sn 21460			
M	ead Finish fount Compound fold Compound	i	HNA, PHI, CDA NiPdAu, Matte 400194 4226215 4226215 + 42 450214	T, JCETC8 Sn 21460			
M M B	ead Finish Nount Compound Nold Compound Sond wire type		HNA, PHI, CDA NiPdAu, Matte 400194 4226215 4226215 + 42 450214 131010100455 4222198 Au, Cu	T, JCETC8 Sn 21460			
M M B	ead Finish fount Compound fold Compound		HNA, PHI, CDA NiPdAu, Matte 400194 4226215 4226215 + 42 450214 131010100455 4222198	T, JCETC8 Sn 21460			
M M B B	ead Finish Nount Compound Nold Compound Sond wire type		HNA, PHI, CDA NiPdAu, Matte 400194 4226215 4226215 + 42 450214 131010100455 4222198 Au, Cu	T, JCETC8 Sn 21460			
M Ba Ba Reason Continuit	ead Finish flount Compound flold Compound flond wire type flond wire diame for Change: ty of Supply	ter	HNA, PHI, CDA NiPdAu, Matte 400194 4226215 4226215 + 42 450214 131010100455 4222198 Au, Cu 0.8 mil	T, JCETC8 Sn 21460			
M Ba Ba Reason Continuit	ead Finish flount Compound flold Compound flond wire type flond wire diame for Change: ty of Supply	ter	HNA, PHI, CDA NiPdAu, Matte 400194 4226215 4226215 + 42 450214 131010100455 4222198 Au, Cu 0.8 mil	T, JCETC8 Sn 21460	lia bilit	y (positi	ve / negative):
M BB BB Reason Continuit	ead Finish flount Compound flold Compound flond wire type flond wire diame for Change: ty of Supply	ter	HNA, PHI, CDA NiPdAu, Matte 400194 4226215 4226215 + 42 450214 131010100455 4222198 Au, Cu 0.8 mil	T, JCETC8 Sn 21460	lia bilit	y (positi	ve / negative):
M Be Be Continuit Anticipa None	ead Finish flount Compound flold Compound flond wire type flond wire diame for Change: ty of Supply	ter 1 Fit, Form	HNA, PHI, CDA NiPdAu, Matte 400194 4226215 4226215 + 42 450214 131010100455 4222198 Au, Cu 0.8 mil	T, JCETC8 Sn 21460	lia bilit	y (positi	ve / negative):
M Both Both Reason Continuit Anticipa None Impact Checked	dount Compound fold Compound fond wire type for Change: ty of Supply ated impact on on Environme boxes indicate	Fit, Form	HNA, PHI, CDA NiPdAu, Matte 400194 4226215 4226215 + 42 450214 131010100455 4222198 Au, Cu 0.8 mil	T, JCETC8 Sn 21460 S ality or Re	llowing	imple me	ntation of this
M Be B	dount Compound fold Compound fond wire type for Change: ty of Supply ated impact on on Environme boxes indicate	ntal Ration the status are checke	HNA, PHI, CDA NiPdAu, Matte 400194 4226215 4226215 + 42 450214 131010100455 4222198 Au, Cu 0.8 mil	T, JCETC8 Sn 21460 S ality or Re	llowing the ass	imple me	ntation of this

Changes to product identification resulting from this PCN:

Assembly Site		
Hana	Assembly Site Origin (22L)	ASO: HNT
TI Philippines	Assembly Site Origin (22L)	ASO: PHI
TI Chengdu	Assembly Site Origin (22L)	ASO: CDA
JCETC8	Assembly Site Origin (22L)	ASO: JC8

Sample product shipping label (not actual product label)





(1P) \$N74L\$07N\$R (Q) 2000 (D) 0336 (31T)LOT: 3959047MLA (4W) TKY(1T) 7523483812 (P) (2P) REV: (V) 0033317

(2P) REV: (V) 0033317 (20L) CSO: SHE (21L) CCO:USA (22L) ASO: MLA (23L) ACO: MYS

Product Affected:

74AVC1T45DRLR	SN74AUC1G32DRLR	SN74LVC1G07DRLR	TMP1075NDRLR
INA185A1IDRLR	SN74AUC2G34DRLR	SN74LVC1G125DRLR	TMP112BIDRLR
INA185A1IDRLT	SN74AUP1G00DRLR	SN74LVC1G126DRLR	TMP112NAIDRLR
INA185A3IDRLR	SN74AUP1G02DRLR	SN74LVC1G14DRLR	TMP20AIDRLR
INA185A3IDRLT	SN74AUP1G04DRLR	SN74LVC1G17DRLR	TMP302DDRLR
INA185A4IDRLR	SN74AUP1G06DRLR	SN74LVC1G19DRLR	TMP303ADRLR
OPA170AIDRLR	SN74AUP1G07DRLR	SN74LVC1G3157DRLR	TMP303BDRLR
OPA170AIDRLT	SN74AUP1G08DRLR	SN74LVC1G332DRLR	TMP303CDRLR
OPA171AIDRLR	SN74AUP1G125DRLR	SN74LVC1G34DRLR	TMP303DDRLR
OPA171AIDRLT	SN74AUP1G126DRLR	SN74LVC1G57DRLR	TMP303EDRLR
SN1511004DRLR	SN74AUP1G14DRLR	SN74LVC1G58DRLR	TMP303FDRLR
SN1511004DRLT	SN74AUP1G17DRLR	SN74LVC1G66DRLR	TMP303GDRLR
SN1608035DRLR	SN74AUP1G34DRLR	SN74LVC1G79DRLR	TMP390A2DRLR
SN1710027DRLR	SN74AUP1G57DRLR	SN74LVC1G86DRLR	TMP390A3DRLR
SN1710027DRLT	SN74AUP1G58DRLR	SN74LVC1G97DRLR	TMP392A2DRLR
SN74AUC1G00DRLR	SN74AUP1G79DRLR	SN74LVC1G98DRLR	TMP392A3DRLR
SN74AUC1G02DRLR	SN74AUP1G97DRLR	SN74LVC1GU04DRLR	TPD2E1B06DRLR
SN74AUC1G04DRLR	SN74AUP1G98DRLR	SN74LVC1GX04DRLR	TPD4E1B06DRLR
SN74AUC1G08DRLR	SN74AVC1T45DRLR	SN74LVC1T45DRLR	
SN74AUC1G17DRLR	SN74LVC1G00DRLR	SN74LVC2G04DRLR	
SN74AUC1G19DRLR	SN74LVC1G06DRLR	SN74LVC2G34DRLR	

Qualification Report

(SOT-5X3) Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Data Displayed as. Number of lots / Total sample size / Total falled					
	Stress Test	Duration	PHI TLV62568DRL	CDAT TPS562231 DRL 1P1T45 DRL R	
тс	Temperature Cycling -65/150C Or Temperature Cycling -55/125C	500 Cycles Or 700 Cycles	3/231/0	3/231/0	
HAST/THB	Biased HAST 130C/85%RH Or Biased HAST 110C/85%RH Or Temperature Humidity Bias, 85C/85%RH	96 hours Or 264 hours Or 1000 hours	3/231/0	3/231/0	
HTSL	High Temp. Storage Bake 150C Or High Temp. Storage Bake 170C	1000 hours Or 420 hours	3/231/0	3/231/0	
UHAST/AC	Unbiased HAST, 130C/85%RH Or Autoclave 121C	96 hours	3/231/0	3/231/0	
SD	Solderability	8 Hour Steam age or 155C Dry Bake	3/66/0	3/66/0	
MQ	Manufacturability	-	Pass	Pass	

	Stress Test	Duration	JCETC8 TLV62568PDRL	HNA TMP390A2DRL
TC	Temperature Cycling -65/150C Or Temperature Cycling -55/125C	500 Cycles Or 700 Cycles	3/231/0	3/231/0
HAST/THB	Biased HAST 130C/85%RH Or Biased HAST 110C/85%RH Or Temperature Humidity Bias, 85C/85%RH	96 hours Or 264 hours Or 1000 hours	3/231/0	3/231/0
HTSL	High Temp. Storage Bake 150C Or High Temp. Storage Bake 170C	1000 hours Or 420 hours	3/231/0	3/231/0
UHAST/AC	Unbiased HAST, 130C/85%RH Or Autoclave 121C	96 hours	3/231/0	3/231/0
SD	Solderability	8 Hour Steam age or 155C Dry Bake	3/66/0	3/66/0 (a)
MQ	Manufacturability	-	Pass	Pass

All qualification devices in the tables are qualified at L1-260C MSL rating.

Note a - Data collected on SN74AVC1T45DRL

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, and HTSL, as applicable
- The following are equivalent HTSL options based on activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Green/Pb-free Status: Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to Change Management team or your local Field Sales Representative.

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